METHOD AND SYSTEM FOR DETECTING MICRO-CRACKS IN WAFERS

Abstract

An inspection method comprises receiving light emanating from a first surface of a wafer substantially along a first axis for obtaining a first image of the first surface therefrom, the wafer having a crack formed therein and the first image containing at least one portion of the crack. The inspection method also comprises receiving light emanating from the first surface of the wafer substantially along a second axis for obtaining a second image of the first surface therefrom, the second image containing at least one second portion of the crack, the first surface extending substantially parallel a plane, and the orthographic projection of the first axis on the plane being substantially perpendicular the orthographic projection of the second axis on the plane. The inspection method further comprises constructing a third image from the at least one first portion of the crack and the least one second portion of the crack of the first and second images respectively. More specifically, the third image is substantially processable for inspecting the crack in the wafer.

FIG. 3

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